

# Field-Emission-Induced Electromigration for Integration and Control of Nanogaps

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## ① Introduction: Field-Emission-Induced Electromigration (Activation)

### Activation: Simple and Easy Fabrication Technique of Tunnel Devices

#### I Wide-Range Control of Tunnel Resistance of Nanogaps

S. Kayashima, K. Takahashi, M. Motoyama, and J. Shirakashi, Jpn. J. Appl. Phys. 46 (2007) L907.  
 S. Kayashima, K. Takahashi, M. Motoyama, and J. Shirakashi, J. Phys. Conf. Ser. 100 (2008) 052022.  
 Y. Tomoda, K. Takahashi, M. Hanada, W. Kume, and J. Shirakashi, J. Vac. Sci. & Technol. B 27 (2009) 813.

#### II Ni/Vacuum/Ni Based Ferromagnetic Tunnel Junctions (MTJs)

Y. Tomoda, M. Hanada, W. Kume, S. Itami, T. Watanabe, and J. Shirakashi, J. Phys. Conf. Ser. 200 (2010) 062035.  
 Y. Tomoda, K. Takahashi, M. Hanada, W. Kume, S. Itami, T. Watanabe, and J. Shirakashi, IEEE Trans. Mag. 45 (2009) 3480.

#### III Fabrication of Single-Electron Transistors (SETs)

W. Kume, Y. Tomoda, M. Hanada, and J. Shirakashi, J. Nanosci. Nanotechnol. 10 (2010) 7239.

#### IV Integration of Two SETs

S. Ueno, Y. Tomoda, W. Kume, M. Hanada, K. Takiya, and J. Shirakashi, J. Nanosci. Nanotechnol. (2011), in print.  
 S. Ueno, Y. Tomoda, W. Kume, M. Hanada, K. Takiya, and J. Shirakashi, Appl. Surf. Sci. (2011), in print.

### → Preset Current: Dominant Parameter for Controlling Electrical Properties of Nanogaps

## ② Schematic of Integration Process during Activation

**Control Parameters**

Temperature: 300 K  
 Environment: Vacuum  
 Preset Current  $I_s$ :  
 1 nA ~ 30  $\mu$ A

**Samples**

Material: Ni  
 Thickness: 20 ~ 30 nm  
 Initial Gap Separation  
 Sample 1:  $W_1 = 114$  nm  
 Sample 2:  $W_2 = 80$  nm  
 Sample 3:  $W_3 = 108$  nm

**Activation Procedure with Current Source**

● Activated Ni Atom   ● Ni Atom   ● Electron

**Flowchart of Experimental Procedure**

```

            graph TD
            START --> A[Apply Initial Current]
            A --> B{Preset Current = Field-Emission Current}
            B -- No --> C[Increase Current]
            C --> B
            B -- Yes --> D[Stop Current Flow]
            D --> E[Sample X1]
            D --> F[Sample X2]
            E --> G[Measure I-V Characteristics]
            F --> H[Measure I-V Characteristics]
            G --> I[Update Preset Current]
            H --> I
            I --> J[END]
            
```

## ③ Simultaneous Tuning of Tunnel Resistance of Nanogaps by Activation

**SEM Images of Series-Connected Nanogaps**

	Sample 1	Sample 2	Sample 3
<b>Before Activation</b>			
<b>Wide Separation of Initial Gaps</b>			
<b>After Activation @ <math>I_s = 30 \mu</math>A</b>			
<b>Accumulation of Ni Atoms within The Gaps</b>			

**I-V Properties of Samples After Performing Activation**

	Sample 1	Sample 2	Sample 3
$I_s = 1$ nA <b>Insulating</b>			
$I_s = 500$ nA <b>Tunneling</b>			
$I_s = 30 \mu$ A <b>Metallic</b>			

**Dependence of Resistances of Nanogaps on Preset Current  $I_s$**

**Electrical Properties Are Simultaneously Tuned by Activation**

## ④ Conclusions

- **SEM Images of Series-Connected Nanogaps After Performing Activation**
  - Separation of gaps was simultaneously reduced to less than 10 nm after activation @  $I_s = 30 \mu$ A.
  - ⇒ Nanogaps with Precisely Controlled Gap Separations
- **Current-Voltage Properties of Simultaneously Activated Nanogaps Connected in Series**
  - Current-voltage characteristics of samples were simultaneously varied from insulating to metallic through tunneling properties.
  - ⇒ Simultaneous Tuning of Electrical Properties of Integrated Nanogaps
- **Tunnel Resistance of Nanogaps vs. Preset Current during Activation**
  - Tunnel resistances of series-connected nanogaps decreased ranging from the order of 100 T $\Omega$  to 100 k $\Omega$ .
  - ⇒ Self-Regulation with Final Spacing Set by Applied Current